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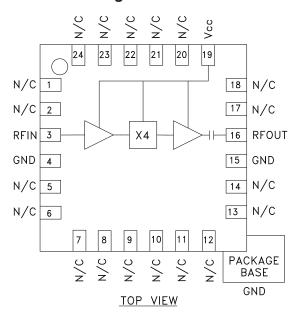
SMT GaAs HBT MMIC x4 ACTIVE FREQUENCY MULTIPLIER, 14.4 - 16.4 GHz OUTPUT

Typical Applications

The HMC370LP4(E) is ideal for:

- Point-to-Point & VSAT Radios
- Fiber Optic
- Military

Functional Diagram



Features

Output Power: 0 dBm

Sub-Harmonic Suppression: >22 dBc

SSB Phase Noise: -140 dBc/Hz Single Supply: +5V @ 55 mA

24 Lead 4x4 mm SMT Package: 16 mm²

General Description

The HMC370LP4(E) is an active miniature x4 frequency multiplier utilizing InGaP GaAs HBT technology in a 4x4 mm leadless surface mount package. Power output is 0 dBm typical from a 5V supply voltage and varies little vs. input power, temperature and supply voltage. Suppression of undesired fundamental and sub-harmonics is >22 dBc typical with respect to output signal level. The low additive SSB phase noise of -140 dBc/Hz at 100 kHz offset helps the user maintain good system noise performance. The HMC370LP4(E) are ideal for use in LO multiplier chains allowing reduced parts count vs. traditional approaches.

Electrical Specifications, $T_A = +25^{\circ}$ C, Vcc = 5V

Parameter	Min.	Тур.	Max.	Units
Frequency Range, Input	3.6 - 4.1		GHz	
Frequency Range, Output	14.4 - 16.4		GHz	
Input Power Range	-15		+5	dBm
Output Power	-4	0		dBm
Sub-Harmonic Suppression		22		dBc
Input Return Loss		18		dB
Output Return Loss		7		dB
SSB Phase Noise (100 kHz Offset) Pin = 0 dBm		-140		dBc/Hz
Supply Current (Icc)		55	73	mA

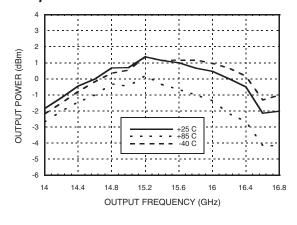


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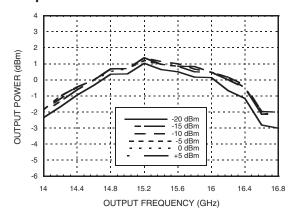


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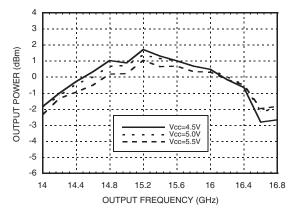
Output Power vs. Temperature @ -10 dBm Drive Level



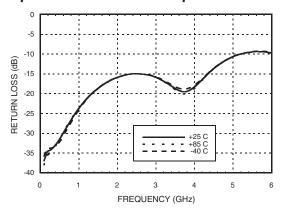
Output Power vs. Drive Level



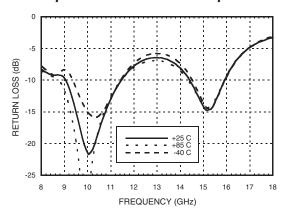
Output Power vs. Supply Voltage @ -10 dBm Drive Level



Input Return Loss vs. Temperature



Output Return Loss vs. Temperature



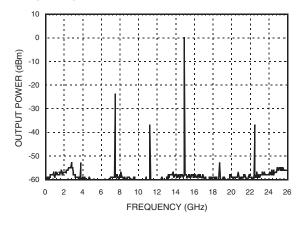


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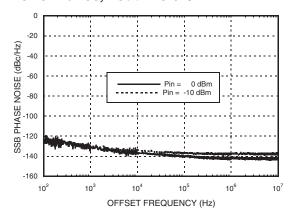


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Output Spectrum



SSB Phase Noise Performance, Fout= 15.0 GHz





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SMT GaAs HBT MMIC x4 ACTIVE FREQUENCY MULTIPLIER, 14.4 - 16.4 GHz OUTPUT

Absolute Maximum Ratings

+20 dBm
+5.5V
135 °C
530 mW
123.6 °C/W
-65 to +150 °C
-40 to +85 °C

Typical Supply Current vs. Vcc

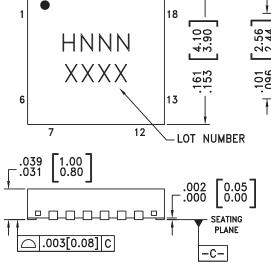
Vcc (V)	Icc (mA)	
4.5	54	
5.0	55	
5.5	57	

Note: Multiplier will operate over full voltage range shown above.

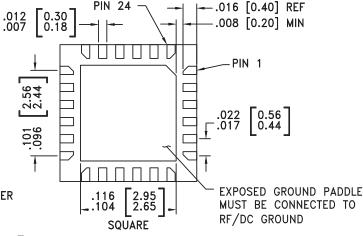


ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

Outline Drawing



BOTTOM VIEW



NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC370LP4	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H370 XXXX
HMC370LP4E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H370 XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX



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Pin Description

Pin Number	Function	Description	Interface Schematic
1, 2, 5-14, 17, 18, 20-24	N/C	The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
3	RFIN	RF input needs to be DC blocked only if there is an external DC voltage applied to RF IN.	RFIN ○
4, 15	GND	All ground leads and ground paddle must be soldered to PCB RF/DC ground.	⊖ GND
16	RFOUT	Multiplied Output. AC coupled. No external DC blocks necessary.	— —○ RFOUT
19	Vcc	Supply voltage 5V ± 0.5V.	